

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1022	438/462	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/06 15:35
L2	167	438/461	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/06 15:45
L3	1028	438/460	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/06 16:50
L4	3	"6803292".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/06 16:05
L5	2659	257/692	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/06 16:51
S1	879	438/462	USPAT	OR	OFF	2005/07/06 14:42
S2	118	438/462	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/10 19:17
S3	472449	(semiconductor or die or chip or IC) and (scrib\$3 or cut\$4 or dicing)	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/10 19:20
S4	205108	(semiconductor or die or chip or IC) and (scrib\$3 or cut\$4 or dicing)	USPAT	OR	OFF	2005/01/10 19:20
S5	30686	(semiconductor or die or chip or IC) and (scrib\$3 or cut\$4 or dicing) and wafer	USPAT	OR	OFF	2005/01/10 19:20

S7	10	(semiconductor or die or chip or IC) and (scrib\$3 or cut\$4 or dicing) with sacrificing and wafer	USPAT	OR	OFF	2005/01/10 19:21
S8	497	(semiconductor or die or chip or IC) and (scrib\$3 or cut\$4 or dicing) and wafer and sacrificing	USPAT	OR	OFF	2005/01/11 14:27
S9	2375	(semiconductor or die or chip or IC) and (scrib\$3 or cut\$4 or dicing) and wafer and (sacrific\$3 or removeable)	USPAT	OR	OFF	2005/01/11 14:28
S10	2340	(semiconductor or die or chip or IC) and (scrib\$3 or cut\$4 or dicing) and wafer and (sacrific\$3 or (removeable with (insulat\$3 or dielectric or epoxy or resist or polymer or resin)))	USPAT	OR	OFF	2005/01/11 14:34
S11	2339	(semiconductor or die or chip or IC) and (scrib\$3 or cut\$4 or dicing) and wafer and (sacrific\$3 or (removeable with (insulat\$3 or dielectric or epoxy or resist or polymer or resin) with (trench or opening or cavity or recess or open or aperture)))	USPAT	OR	OFF	2005/01/11 18:29
S12	227	S11 and (sacrific\$3 or (removeable with (insulat\$3 or dielectric or epoxy or resist or polymer or resin) with (trench or opening or cavity or recess or open or aperture))) with (channel or grove or hole or via)	USPAT	OR	OFF	2005/01/11 15:09
S13	2500	(semiconductor or die or chip or IC) and (scrib\$3 or cut\$4 or dicing) and wafer and (sacrific\$3 or (removeable with (insulat\$3 or dielectric or epoxy or resist or polymer or resin) with (trench or opening or cavity or recess or open or aperture)))	USPAT	OR	ON	2005/01/11 15:08
S14	410	S13 and (sacrific\$3 or (removeable with (insulat\$3 or dielectric or epoxy or resist or polymer or resin) with (trench or opening or cavity or recess or open or aperture))) with (channel or grove or hole or via)	USPAT	OR	ON	2005/01/11 18:30

S15	2339	(semiconductor or die or chip or IC) and (scrib\$3 or cut\$4 or dicing) and wafer and (sacrific\$3 or (removeable with (insulat\$3 or dielectric or epoxy or resist or polymer or resin) with (trench or opening or cavity or recess or open or aperture)))	USPAT	OR	OFF	2005/01/11 18:29
S16	2500	(semiconductor or die or chip or IC) and (scrib\$3 or cut\$4 or dicing) and wafer and (sacrific\$3 or (removeable with (insulat\$3 or dielectric or epoxy or resist or polymer or resin) with (trench or opening or cavity or recess or open or aperture)))	USPAT	OR	ON	2005/01/11 18:30
S17	410	S16 and (sacrific\$3 or (removeable with (insulat\$3 or dielectric or epoxy or resist or polymer or resin) with (trench or opening or cavity or recess or open or aperture))) with (channel or grove or hole or via)	USPAT	OR	ON	2005/01/11 18:30
S18	1944	S15 not S17	USPAT	OR	ON	2005/01/11 18:31
S19	161	S16 not S15	USPAT	OR	ON	2005/01/11 18:32
S20	168	438/461	USPAT	OR	OFF	2005/01/18 15:59
S21	944	438/460	USPAT	OR	OFF	2005/01/18 15:59
S22	850	pattern near plating	USPAT	OR	OFF	2005/01/18 21:31
S23	126	"438"/\$.ccls. and pattern near plating	USPAT	OR	OFF	2005/01/18 21:31
S24	24	pattern near plating with resist near layer	USPAT	OR	OFF	2005/01/18 21:31
S25	30	pattern near plating with (resist or mask) near layer	USPAT	OR	OFF	2005/01/18 22:23
S26	199	substrate with socket and (semiconductor or die or chip) with pin	USPAT	OR	OFF	2005/01/18 22:37
S27	45	substrate with socket and (semiconductor or die or chip) with pin and substrate with (adhesive or glue)	USPAT	OR	OFF	2005/01/18 22:49
S28	78	(module or board) with socket and (semiconductor or die or chip) with pin and (module or board) with (adhesive or glue)	USPAT	OR	OFF	2005/01/18 23:01

S29	11	(module or board) with socket and (semiconductor or die or chip) with pin and (module or board) with (adhesive or glue) same socket	USPAT	OR	OFF	2005/01/18 22:52
S30	205	(substrate or module or board) with socket and (semiconductor or die or chip) with lead and (substrate or module or board) with (adhesive or glue)	USPAT	OR	OFF	2005/01/18 23:28
S31	1145	(substrate or module or board) with (socket or via) and (semiconductor or die or chip) with lead and (substrate or module or board) with (adhesive or glue)	USPAT	OR	OFF	2005/01/18 23:28
S32	610	(substrate or module or board) with (socket or via) and (semiconductor or die or chip) with pin and (substrate or module or board) with (adhesive or glue)	USPAT	OR	OFF	2005/01/18 23:29
S33	13	(substrate or module or board) with (socket or via) and (semiconductor or die or chip) with pin and (substrate or module or board) with (adhesive or glue) and via with conductive with coat\$3	USPAT	OR	OFF	2005/01/18 23:33
S34	2	"3401126".PN.	USPAT; USOCR	OR	OFF	2005/01/18 23:31
S35	2	"3429040".PN.	USPAT; USOCR	OR	OFF	2005/01/18 23:31
S36	1	"3915780".PN.	USPAT; USOCR	OR	OFF	2005/01/18 23:31
S37	14	(substrate or module or board) with (socket or via) and (semiconductor or die or chip) with pin and (substrate or module or board) with (adhes\$3 or glu\$3) and via with conductive with coat\$3	USPAT	OR	OFF	2005/01/18 23:33
S38	45	(substrate or module or board) with (socket) and (semiconductor or die or chip) with pin and (substrate or module or board) with (adhes\$3 or glu\$3) and socket with conductive	USPAT	OR	OFF	2005/01/18 23:37

S39	11	(substrate or module or board) with (socket) and (semiconductor or die or chip) with pin and (substrate or module or board) with (underfill\$3)	USPAT	OR	OFF	2005/01/18 23:40
S40	139	(substrate or module or board) with via same socket and (semiconductor or die or chip) with pin	USPAT	OR	OFF	2005/01/18 23:40
S41	1	"3915780".PN.	USPAT; USOCR	OR	OFF	2005/01/19 00:05
S42	1	"4604644".PN.	USPAT; USOCR	OR	OFF	2005/01/19 00:05
S43	1	"4966857".PN.	USPAT; USOCR	OR	OFF	2005/01/19 00:05
S44	1	"5447886".PN.	USPAT; USOCR	OR	OFF	2005/01/19 00:05
S45	1	"5491111".PN.	USPAT; USOCR	OR	OFF	2005/01/19 00:06
S46	1	"5536765".PN.	USPAT; USOCR	OR	OFF	2005/01/19 00:06
S47	1	"5612513".PN.	USPAT; USOCR	OR	OFF	2005/01/19 00:06
S48	1	"5861654".PN.	USPAT; USOCR	OR	OFF	2005/01/19 00:06
S49	1	"5866943".PN.	USPAT; USOCR	OR	OFF	2005/01/19 00:06
S50	1	"5869353".PN.	USPAT; USOCR	OR	OFF	2005/01/19 00:07
S51	1	"5923958".PN.	USPAT; USOCR	OR	OFF	2005/01/19 00:07
S52	1	"6020219".PN.	USPAT; USOCR	OR	OFF	2005/01/19 00:07
S53	1	"6087202".PN.	USPAT; USOCR	OR	OFF	2005/01/19 00:07
S54	1	"6087202".PN.	USPAT; USOCR	OR	OFF	2005/01/19 00:07
S55	1	"6100108".PN.	USPAT; USOCR	OR	OFF	2005/01/19 00:07
S56	1	"6316289".PN.	USPAT; USOCR	OR	OFF	2005/01/19 00:07
S57	37	"6110823"	USPAT	OR	OFF	2005/01/19 00:08
S58	3	patterned near mask near layer with (polymer and photoresist)	USPAT	OR	OFF	2005/01/19 06:02
S59	2050	barrier near layer with (polymer)	USPAT	OR	OFF	2005/01/19 06:03

S60	95	barrier near layer with (polymer) with adhesion	USPAT	OR	OFF	2005/01/19 06:15
S61	0	barrier near layer with (polymer) with before with metal near plug	USPAT	OR	OFF	2005/01/19 06:15
S62	4	barrier near layer with (polymer) with before with metal	USPAT	OR	OFF	2005/01/19 06:19
S63	9	barrier near layer with (polymer) with (before or prior) with metal	USPAT	OR	OFF	2005/01/19 06:20
S64	173	barrier near layer with (polymer) with metal	USPAT	OR	OFF	2005/01/19 06:34
S65	32	adhesive near layer with (polymer) and adhesive near layer with between with substrate with (metal or wir\$3)	USPAT	OR	OFF	2005/01/19 06:39
S66	154	adhesive near layer with (polymer) and adhesive near layer with substrate with (metal or wir\$3)	USPAT	OR	OFF	2005/01/19 06:39
S67	27	adhesive near layer near (polymer) and adhesive near layer with substrate with (metal or wir\$3)	USPAT	OR	OFF	2005/01/19 06:42
S68	252	adhesive near (polymer) and adhesive near layer with (metal or wir\$3)	USPAT	OR	OFF	2005/01/19 06:43
S69	14	adhesive near (polymer) and adhesive near layer with (metal or wir\$3) with barrier	USPAT	OR	OFF	2005/01/19 06:44
S70	77	adhesive near (polymer) with barrier	USPAT	OR	OFF	2005/01/19 06:45
S71	34	adhesive near (polymer) with barrier and (semiconductor or die or chip or IC)	USPAT	OR	OFF	2005/01/19 06:47
S72	164	adhesive near (polymer) with (conductive or wir\$3) and (semiconductor or die or chip or IC)	USPAT	OR	OFF	2005/01/19 07:01
S73	0	adhesive near (polymer and silicon near oxide) with (conductive or wir\$3) and (semiconductor or die or chip or IC)	USPAT	OR	OFF	2005/01/19 07:01
S74	0	adhesive near (polymer and silicon near oxide) same (conductive or wir\$3) and (semiconductor or die or chip or IC)	USPAT	OR	OFF	2005/01/19 07:02
S75	0	adhesive near (polymer and silicon near oxide)	USPAT	OR	OFF	2005/01/19 07:02
S76	56	adhesive with (polymer and silicon near oxide)	USPAT	OR	OFF	2005/01/19 07:02

S77	0	adhesive with (polymer and silicon near oxide) same (conductive or wir\$3) and (semiconductor or die or chip or IC)	USPAT	OR	OFF	2005/01/19 07:02
S78	32	adhesive with (polymer and silicon near oxide) and (semiconductor or die or chip or IC)	USPAT	OR	OFF	2005/01/19 07:57
S79	229	438/460	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/19 07:58
S80	168	438/461	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/19 08:00
S81	121	438/462	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/19 08:00